

CARD EDGE CONNECTORS

.100" X .200" [2.54 X 5.08] CENTERLINE
CF SFRIFS

INTRODUCTION:

ADAM TECHNOLOGIES

Adam Tech CE Series Card Edge Connectors are precision engineered PCB mount connectors developed to mate with the plated fingers of a printed circuit daughter board. Their bifurcated, cantilever contacts are set in a dual readout configuration and they offer a reliable connection for wide range of PCB thicknesses. Adam Tech's sturdy solder tails with tapers allow easy insertion and rugged durability.

FEATURES:

.100" x .200" centerlines Selectively gold plated contacts Wide selection of positions Compatible with a wide range of PCB thicknesses

MATING PC BOARDS:

All printed circuit boards with a thickness of .055" to .075"

SPECIFICATIONS:

Material:

Insulator: PBT, 30% glass reinforced, rated UL94V-0

Insulator Color: Black Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 µin Optional) over Nickel underplate on contact area,

tin over copper underplate on tails.

Electrical:

Operating voltage: 250V AC max.
Current rating: 3 Amps max.

Contact resistance: 30 m Ω max. initial Insulation resistance: 3000 M Ω min.

Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 10 oz max. Withdrawal force: 3 oz min **Temperature Rating:**

Operating temperature: -40°C to +105°C

PACKAGING:

Anti-ESD plastic trays

SAFETY AGENCY APPROVALS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596

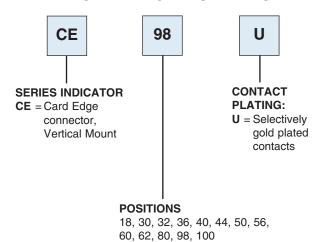








ORDERING INFORMATION



OPTIONS:

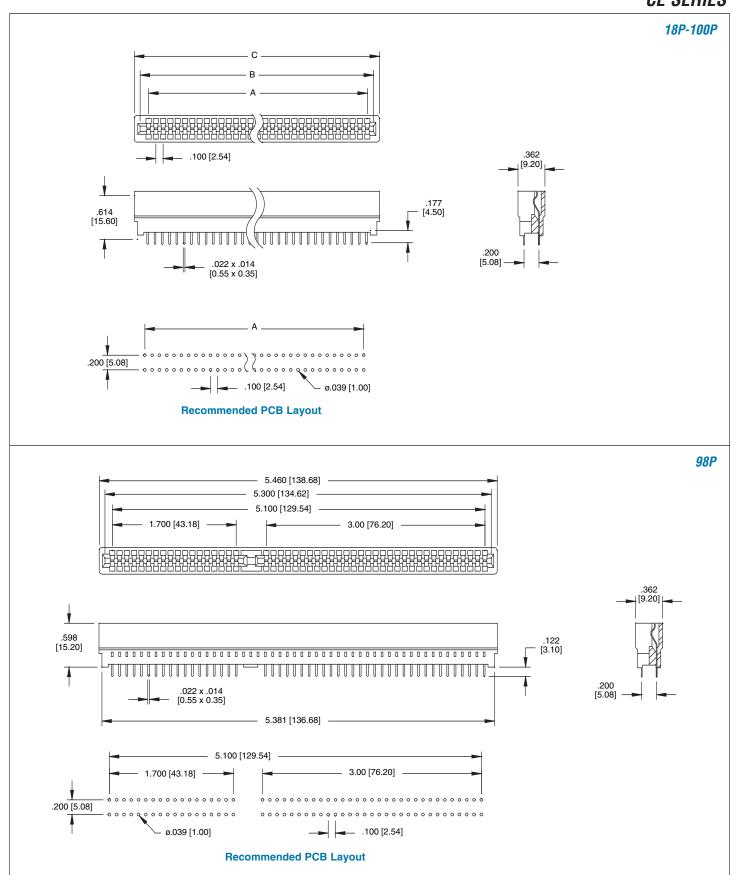
Add designator(s) to end of part number 30 = 30 µin gold plating in contact area RC = RoHS compliant lead-free product with Hi-Temp insulator



ADAM TECHNOLOGIES

CARD EDGE CONNECTORS

.100" X .200" [2.54 X 5.08] CENTERLINE CE SERIES





.050" [1.27] CENTERLINE EISA CONNECTOR HDCE SERIES

INTRODUCTION:

ADAM TECHNOLOGIES

Adam Tech HDCE Series EISA (Extended Industry Standard Architecture) Card Edge Connectors are .050" pitch 188 position dual level contact connectors specifically designed to mate with AT, XT and PC expansion cards. Our precision formed High Reliability contact system is contained within a Hi-Temp PPS body which features a close tolerance polarizing slot and card edge lead-in area for superior mating.

FEATURES:

High density .050" Centerlines Compatible with PC, XT & AT Durable Long Life cycle contacts High Pressure Contacts for Low Level Circuits

MATING PC BOARDS:

All .050" centerline printed circuit board pads with a thickness of .062 to .072" $\,$

SPECIFICATIONS:

Material:

Insulator: PPS, 30% glass reinforced, rated UL94V-0 Insulator Color: Dark Brown (White optional)

Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 µin Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 125V AC max. Current rating: 3 Amps max.

Contact resistance: 20 m Ω max. initial Insulation resistance: 1000 M Ω min.

Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 7 oz max. Withdrawal force: 0.9 oz min

Temperature Rating:

Operating temperature: -55°C to +105°C

PACKAGING:

Anti-ESD plastic trays

APPROVALS AND CERTIFICATIONS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596

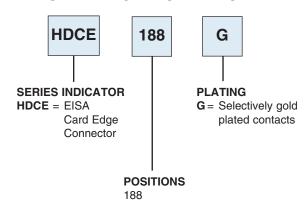








ORDERING INFORMATION



OPTIONS:

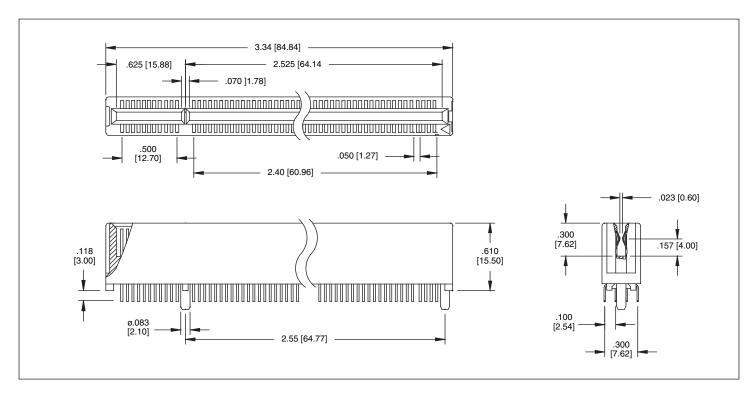
Add designator(s) to end of part number

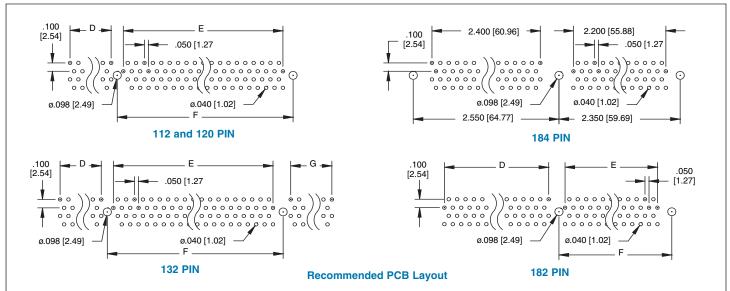
BK = Black color insulation

RC = RoHS compliant lead-free product with Hi-Temp insulator



.050" [1.27] VESA MICRO CHANNEL ARCHITECTURE (MCA) HMCA SERIES





Unit: Inch / mm

Part No. & Positions	Dimensions:						
	Α	В	С	D	E	F	G
HMCA-112-G	3.140 (79.76)	0.625 (15.88)	2.325 (59.06)	0.500 (12.70)	2.200 (55.88)	2.232 (56.69)	_
HMCA-120-G	3.340 (84.84)	0.625 (15.88)	2.525 (64.14)	0.500 (12.70)	2.400 (60.96)	2.550 (64.77)	_
HMCA-132-G	3.740 (95.00)	0.625 (15.88)	2.925 (74.30)	1.834 (46.60)	2.200 (55.88)	2.350 (59.69)	0.450 (11.43)
HMCA-182-G	4.890 (124.21)	2.175 (55.25)	2.525 (64.14)	2.050 (52.07)	2.050 (52.07)	2.550 (64.77)	_
HMCA-194-G	5.290 (134.37)	2.175 (55.25)	2.925 (74.30)	2.050 (52.07)	2.200 (55.88)	2.350 (55.88)	0.450 (11.43)



.050" [1.27] VESA MICRO CHANNEL
ARCHITECTURE (MCA)
HMCA SERIES

INTRODUCTION:

ADAM TECHNOLOGIES

Adam Tech HMCA Series Card Edge Connectors include Standard and Express versions designed for PCB's in Peripheral Component Interconnect (PCI) applications. Each is manufactured in a four row, high density package which is completely compatible to industry standards and has specially engineered contacts which provide a very short electrical path between boards. Adam Tech card edge connectors are designed for high performance with solid board pegs and precision located, selectively gold plated contacts which are ideal in high speed, increased bandwidth applications

FEATURES:

PCI and PCI Express Versions
High density compact designs
Industry standard PCI compatible
Special contact design reduces electrical path
Selectively plated contacts
Open bottom for after solder cleaning

MATING PC BOARDS:

All .050" centerline printed circuit board pads with a thickness of .062 to .072"

SPECIFICATIONS:

Material:

Insulator: PPS, 30% glass reinforced, rated UL94V-0 Insulator Color: Dark Brown (White 120 pos.)

Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 μ in Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 125V AC max. Current rating: 1 Amps max.

Contact resistance: 30 m Ω max. initial Insulation resistance: 1000 M Ω min.

Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 7 oz max. Withdrawal force: 0.9 oz min

Temperature Rating:

Operating temperature: -55°C to +105°C

PACKAGING:

Anti-ESD plastic trays

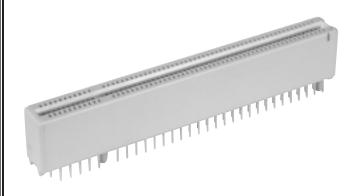
SAFETY AGENCY APPROVALS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596

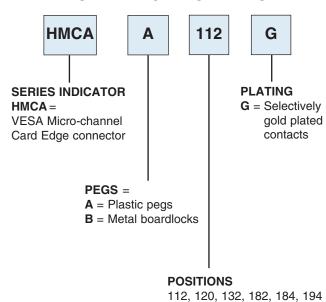








ORDERING INFORMATION



OPTIONS

Add designator(s) to end of part number

RC = RoHS compliant lead-free product

with Hi-Temp insulator



.050" [1.27] CENTERLINE EISA CONNECTOR HDCE SERIES

